Product Change Notification - KSRA-04FQJT080

Date:

24 May 2018 **Product Category:** Memory **Notification subject:** CCB 3089 Final Notice: Qualification of UNIS as a new assembly site for selected Atmel Memory products available in 8L WLCSP package. **Notification text: PCN Status:** Final notification.

PCN Type: Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:

Qualification of UNIS as a new assembly site for selected Atmel Memory products available in 8L WLCSP package.

Pre Change: Assembled at ASE

Post Change: Assembled at UNIS

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	ASE Inc. (Bumping/WLCSP) (ASE)	Unisem (M) Berhad Perak, Malaysia (UNIS)
Redistribution Layer (RDL)	Ti(sp)-Al(sp)-Ti(sp)	Ti(sp)-Cu(sp)-Cu(pl)
Under Bump Metallurgy (UBM)	ASEKH Al(sp)-NiV(sp)- Cu(sp)	Ti(sp)-Cu(sp)-Cu(pl)
Solder Ball	SAC 405	SAC 405

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve on time delivery performance by qualifying UNIS as new assembly site

Change Implementation Status:

In Progress

Estimated First Ship Date:

June 24, 2018 (date code: 1826)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	September 2017				May 2018				June 2018						
Workweek	35	36	37	38	39	->	18	19	20	21	22	23	24	25	26
Initial PCN Issue Date		х													
Qual Report Availability										Х					
Final PCN Issue Date										Х					
Estimated Implementation Date															х

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:

September 12, 2017: Issued initial notification.

May 24, 2018: Issued final notification. Attached the qualification report. Removed one assembly site under pre-change and updated affected parts list to match with the updated scope. Provided estimated first ship date to be on June 24, 2018.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_KSRA-04FQJT080_QUAL REPORT.pdf

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

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To opt out of future offer or information emails (other than product change notification emails), click here to go to <u>microchipDIRECT</u> and login, then click on the "My account" link, click on "Update profile" and un-check the box that states "Future offers or information about Microchip's products or services."

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Affected Catalog Part Numbers (CPN)

AT24C512C-U1UM-T AT24C512C-UUMEY-T AT24C512C-UUMHC-T AT24C512C-UUMHC-T-020 AT24CM01-U1UMGY-T AT24CM01-U1UMGY-T-020 AT24CM01-U2UMHJ-T AT24CM01-UUMJC-T-923 AT24CM01-UUM-T AT24CM02-U2UM-T AT25080B-UULHN-T AT250801-UUM-T